LM2941QML

LM2941QML 1A Low Dropout Adjustable Regulator

Datasheet.Live



Literature Number: SNVS390A



LM2941QML

1A Low Dropout Adjustable Regulator

General Description

The LM2941 positive voltage regulator features the ability to source 1A of output current with a typical dropout voltage of 0.5V and a maximum of 1V over the entire temperature range. Furthermore, a quiescent current reduction circuit has been included which reduces the ground pin current when the differential between the input voltage and the output voltage exceeds approximately 3V. The quiescent current with 1A of output current and an input-output differential of 5V is therefore only 30mA. Higher quiescent currents only exist when the regulator is in the dropout mode ($V_1 - V_0 \le 3V$).

Originally designed for vehicular applications, the LM2941 and all regulated circuitry are protected from reverse battery installations or two-battery jumps. During line transients, such as load dump when the input voltage can momentarily exceed the specified maximum operating voltage, the regulator will automatically shut down to protect both the internal circuits

and the load. Familiar regulator features such as short circuit and thermal overload protection are also provided.

Features

- Available with radiation guarantee
 ELDRS Free
- 100 krad(Si)
- Output voltage adjustable from 5V to 20V
- Dropout voltage typically 0.5V @ I_O = 1A
- Output current in excess of 1A
- Trimmed reference voltage
- Reverse battery protection
- Internal short circuit current limit
- Mirror image insertion protection
- TTL, CMOS compatible ON/OFF switch

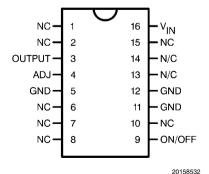
Ordering Information

NS Part Number	SMD Part Number	NS Package Number	Package Description
LM2941WG/883	5962-9166701QYA	WG16A	16LD Ceramic SOIC
LM2941WG-QMLV	5962-9166701VYA	WG16A	16LD Ceramic SOIC
LM2941WGRLQMLV ELDRS FREE (<i>Note 10</i>)	5962R9166702VYA 100 krad(Si)	WG16A	16LD Ceramic SOIC
LM2941GW/883	5962-9166703QYA	WG16A	16LD Ceramic SOIC
LM2941GW-QMLV	5962-9166703VYA	WG16A	16LD Ceramic SOIC
LM2941GWRLQMLV ELDRS FREE (<i>Note 10</i>)	5962R9166704VYA 100 krad(Si)	WG16A	16LD Ceramic SOIC
LM2941 MDE ELDRS FREE (<i>Note 10</i>)	5962R9166702V9A 100 krad(Si)	(Note 1)	Bare Die

Note 1: FOR ADDITIONAL DIE INFORMATION, PLEASE VISIT THE HI REL WEB SITE AT: www.national.com/analog/space/level die

Connection Diagrams

16-Lead Ceramic Surface Mount Package



Top View
See NS Package Number WG16A

Equivalent Schematic Diagram − V_{OUT} - ADJ - GND ON/OFF 20158501

Absolute Maximum Ratings (Note 2)

Lead Temperature (Soldering, 10 seconds) 300°C

Thermal Resistance

 $\begin{array}{lll} \theta_{JA} & & & & \\ & \text{Ceramic SOIC (Still Air) 'WG'} & & 122^{\circ}\text{C/W} \\ & \text{Ceramic SOIC (500LF/Min Air Flow) 'WG'} & & 77^{\circ}\text{C/W} \\ & \text{Ceramic SOIC (Still Air) 'GW'} & & 136^{\circ}\text{C/W} \\ & \text{Ceramic SOIC (500LF/Min Air Flow) 'GW'} & & 87^{\circ}\text{C/W} \\ & \theta_{JC} & & & & \\ & \text{Ceramic SOIC 'WG'(Note 4)} & & 5^{\circ}\text{C/W} \\ \end{array}$

Ceramic SOIC 'GW'

Package Weight (Typ)

Ceramic SOIC 'WG'

Ceramic SOIC 'GW'

410mg

ESD susceptibility to be determined. (*Note 5*) 500V

Recommended Operating Conditions

Maximum Input Voltage 26V Temperature Range $-55^{\circ}\text{C} \le \text{T}_{\text{A}} \le 125^{\circ}\text{C}$

Quality Conformance Inspection

Mil-Std-883, Method 5005 - Group A

Subgroup Description		Temp °C
1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	7 Functional tests at	
8A	Functional tests at	+125
8B	Functional tests at	
9	9 Switching tests at	
10	Switching tests at	+125
11	11 Switching tests at	
12	2 Settling time at	
13 Settling time at		+125
14	Settling time at	-55

3 www.national.com

13°C/W

LM2941 Electrical Characteristics

DC Parameters

The following conditions apply, unless otherwise specified.

DC: $5V \le V_O \le 20V$, $V_{IN} = V_O + 5V$, $C_O = 22\mu F$

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub- groups
V _{Ref}	Reference Voltage	5mA ≤ I _O ≤ 1A		1.237	1.313	V	1
		-		1.211	1.339	V	2, 3
V _{RLine}	Line Regulation	$V_{O} + 2V \le V_{IN} \le 26V, I_{O} = 5mA$	(Note 8)		10	mV/V	1, 2, 3
	Load Regulation	$50\text{mA} \le I_{\text{O}} \le 1\text{A}, V_{\text{IN}} = 10\text{V},$ $V_{\text{OUT}} = 5\text{V}$	- (Note 8)		10	mV/V	1, 2, 3
V _{RLoad}		$50\text{mA} \le I_{\text{O}} \le 1\text{A}, V_{\text{IN}} = 25\text{V},$ $V_{\text{OUT}} = 20\text{V}$			10	mV/V	1, 2, 3
		$V_{O} + 2V \le V_{IN} \le 26V, I_{O} = 5mA$			15	mA	1
I.	Quiescent Current				20	mA	2, 3
I _Q	Quiescent Gurrent	$V_{IN} = V_O + 5V$, $I_O = 1A$			45	mA	1
					60	mA	2, 3
	Dropout Voltage	I _O = 1A			0.8	V	1
V _{DO}					1.0	V	2, 3
* DO		I _O = 100mA			200	mV	1
					300	mV	2, 3
I _{sc}	Short Circuit Current	V _{IN Max} = 26V		1.6	3.5	Α	1
-50		IN Max — 5		1.3	3.7	Α	2, 3
	Maximum Operational Input Voltage		(Note 7)		26	V _{DC}	1, 2, 3
	Reverse Polarity DC Input Voltage	$R_O = 100\Omega$, $V_O \ge -0.6V$	(Note 6)	-15		V	1, 2, 3
V _{TH On}	ON/OFF Threshold Voltage ON	I _O ≤ 1A	(Note 6)		0.8	V	1, 2, 3
V _{Th Off}	ON/OFF Threshold Voltage OFF	I _O ≤ 1A	(Note 6)	2.00		V	1, 2, 3
	ON/OFF Threshold Current				100	μA	1
	ON OF THE SHOW OWNERS	$V_{ON/OFF} = 2.0V, I_O \le 1A$			300	μΑ	2, 3

AC Parameters

The following conditions apply, unless otherwise specified.

AC: $5V \le V_O \le 20V$, $V_{IN} = V_O + 5V$, $C_O = 22\mu F$

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub- groups
	Maximum Line Transient	V _{O Max} 1V above nominal V _O , R _O		60		V	4, 5, 6
		= 100Ω, t ≤ 100mS					
	Reverse Polarity Transient Input	$t \le 100 \text{mS}, R_{\Omega} = 100 \Omega$		-50		٧	4, 5, 6
	Voltage						
RR	Dipple Dejection	$f_{\rm O}$ = 1KHz, 1 $V_{\rm RMS}$, $I_{\rm L}$ = 100mA	(Note 9)		0.02	%/V	4
nn	Ripple Rejection	$f_{\rm O}$ = 1KHz, 1 $V_{\rm RMS}$, $I_{\rm L}$ = 100mA	(Note 9)		0.04	%/V	5, 6

DC Drift Parameters

The following conditions apply, unless otherwise specified.

DC: $5V \le V_O \le 20V, V_{IN} = V_O + 5V, C_O = 22\mu F$

Delta calculations performed on QMLV devices at group B, subgroup 5.

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub- groups
V_{Ref}	Reference Voltage	5mA ≤ I _O ≤ 1A		-25	+25	mV	1

Note 2: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

Note 3: The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (package junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $P_{Dmax} = (T_{Jmax} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower.

Note 4: The package material for these devices allows much improved heat transfer over our standard ceramic packages. In order to take full advantage of this improved heat transfer, heat sinking must be provided between the package base (directly beneath the die), and either metal traces on, or thermal vias through, the printed circuit board. Without this additional heat sinking, device power dissipation must be calculated using θ_{JA} , rather than θ_{JC} , thermal resistance. It must not be assumed that the device leads will provide substantial heat transfer out of the package, since the thermal resistance of the lead frame material is very poor, relative to the material of the package base. The stated θ_{JC} thermal resistance is for the package material only, and does not account for the additional thermal resistance between the package base and the printed circuit board. The user must determine the value of the additional thermal resistance and must combine this with the stated value for the package, to calculate the total allowed power dissipation for the device.

Note 5: Human body model, $1.5 \text{ k}\Omega$ in series with 100 pF.

Note 6: Functional test go-no-go only.

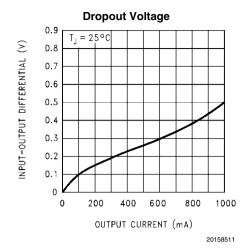
Note 7: Condition for VIN

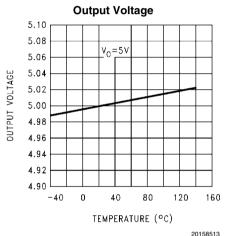
Note 8: Limit = mV per volt of V_{O} .

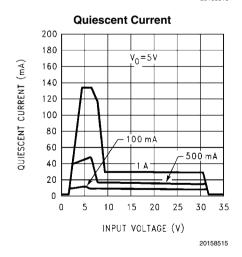
Note 9: %/V = % of V_{IN} per Volt of V_{O} .

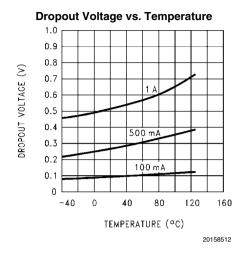
Note 10: These parts are tested on a wafer by wafer basis at high and low dose rates according to MIL-STD-883 Test Method 1019 Conditions A and D with no enhanced low dose rate sensitivity (ELDRS). Pre and post irradiation limits are identical to those listed under AC and DC electrical characteristics.

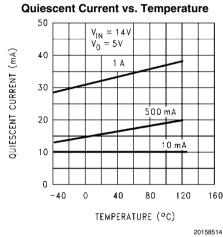
Typical Performance Characteristics

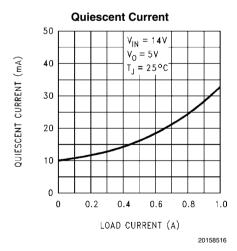


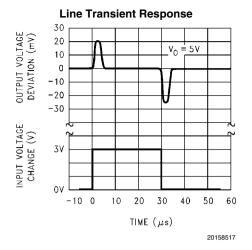


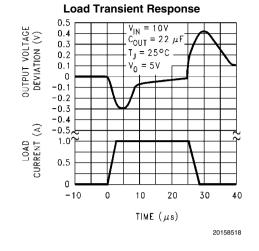


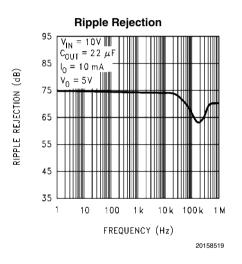


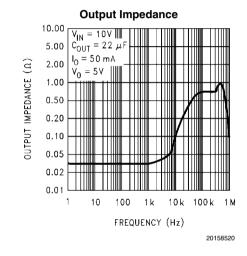


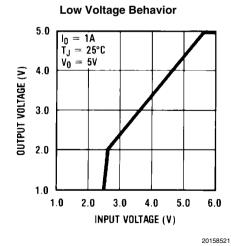


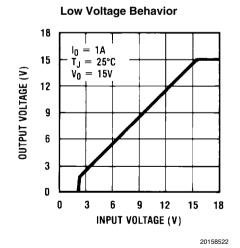


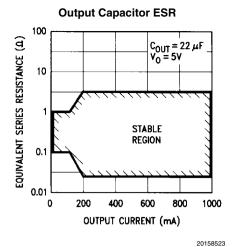


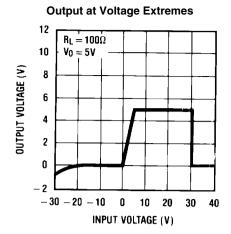






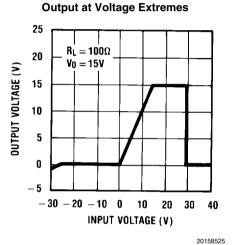






20158524

20158526



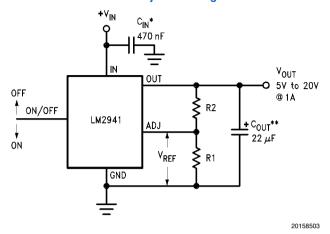
Peak Output Current 3.0 OUTPUT CURRENT (A) v₀ = 5v 2.0 1.0 -40 0 40 80 120 160 TEMPERATURE (°C)

www.national.com

8

Typical Applications

5V to 20V Adjustable Regulator



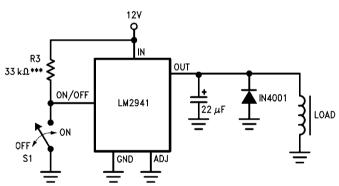
$$\begin{split} &V_{OUT}=\text{Reference voltage} \times \frac{\text{R1}+\text{R2}}{\text{R1}} \text{ where } V_{REF}=\text{1.275 typical} \\ &\text{Solving for R2: } \text{R2}=\text{R1} \left(\frac{V_O}{V_{REF}}-1\right) \end{split}$$

Note: Using 1KΩ for R1 will ensure that the input bias current error of the adjust pin will be negligible. Do not bypass R1 or R2. This will lead to instabilities.

* Required if regulator is located far from power supply filter.

** C₀ must be at least 22µF to maintain stability. May be increased without bound to maintain regulation during transients. Locate as close as possible to the regulator. This capacitor must be rated over the same operating temperature range as the regulator and the ESR is critical; see curve.

1A Switch



9

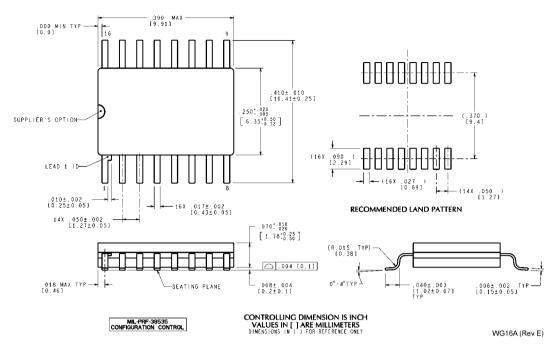
20158506

*** To assure shutdown, select Resistor R3 to guarantee at least 300µA of pull-up current when S1 is open. (Assume 2V at the ON/OFF pin.)

Revision History Section

Released	Revision	Section	Changes
08/25/09	Α	New Release, Corporate format	1 MDS data sheet converted into one Corp. data
			sheet format. Added Radiation products to ordering
			table. MNLM2941-X Rev 4A1 will be archived.
12-Oct-2011	В	Ordering Information, Absolute Max Ratings	Ordering Information — Added LM2941GW/883,
			LM2941GW-QMLV and LM2941GWRLQMLV.
			Absolute Max — Added Theta JA and Theta JC
			along with Package weight of 'GW' devices.
			RatingsLM2941QML Rev A will be archived.

Physical Dimensions inches (millimeters) unless otherwise noted



16LD Ceramic SOIC NS Package Number WG16A

Notes

For more National Semiconductor product information and proven design tools, visit the following Web sites at: www.national.com

Products		Design Support		
Amplifiers	www.national.com/amplifiers	WEBENCH® Tools	www.national.com/webench	
Audio	www.national.com/audio	App Notes	www.national.com/appnotes	
Clock and Timing	www.national.com/timing	Reference Designs	www.national.com/refdesigns	
Data Converters	www.national.com/adc	Samples	www.national.com/samples	
Interface	www.national.com/interface	Eval Boards	www.national.com/evalboards	
LVDS	www.national.com/lvds	Packaging	www.national.com/packaging	
Power Management	www.national.com/power	Green Compliance	www.national.com/quality/green	
Switching Regulators	www.national.com/switchers	Distributors	www.national.com/contacts	
LDOs	www.national.com/ldo	Quality and Reliability	www.national.com/quality	
LED Lighting	www.national.com/led	Feedback/Support	www.national.com/feedback	
Voltage References	www.national.com/vref	Design Made Easy	www.national.com/easy	
PowerWise® Solutions	www.national.com/powerwise	Applications & Markets	www.national.com/solutions	
Serial Digital Interface (SDI)	www.national.com/sdi	Mil/Aero	www.national.com/milaero	
Temperature Sensors	www.national.com/tempsensors	SolarMagic™	www.national.com/solarmagic	
PLL/VCO	www.national.com/wireless	PowerWise® Design University	www.national.com/training	

THE CONTENTS OF THIS DOCUMENT ARE PROVIDED IN CONNECTION WITH NATIONAL SEMICONDUCTOR CORPORATION ("NATIONAL") PRODUCTS. NATIONAL MAKES NO REPRESENTATIONS OR WARRANTIES WITH RESPECT TO THE ACCURACY OR COMPLETENESS OF THE CONTENTS OF THIS PUBLICATION AND RESERVES THE RIGHT TO MAKE CHANGES TO SPECIFICATIONS AND PRODUCT DESCRIPTIONS AT ANY TIME WITHOUT NOTICE. NO LICENSE, WHETHER EXPRESS, IMPLIED, ARISING BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT.

TESTING AND OTHER QUALITY CONTROLS ARE USED TO THE EXTENT NATIONAL DEEMS NECESSARY TO SUPPORT NATIONAL'S PRODUCT WARRANTY. EXCEPT WHERE MANDATED BY GOVERNMENT REQUIREMENTS, TESTING OF ALL PARAMETERS OF EACH PRODUCT IS NOT NECESSARILY PERFORMED. NATIONAL ASSUMES NO LIABILITY FOR APPLICATIONS ASSISTANCE OR BUYER PRODUCT DESIGN. BUYERS ARE RESPONSIBLE FOR THEIR PRODUCTS AND APPLICATIONS USING NATIONAL COMPONENTS. PRIOR TO USING OR DISTRIBUTING ANY PRODUCTS THAT INCLUDE NATIONAL COMPONENTS, BUYERS SHOULD PROVIDE ADEQUATE DESIGN, TESTING AND OPERATING SAFEGUARDS.

EXCEPT AS PROVIDED IN NATIONAL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, NATIONAL ASSUMES NO LIABILITY WHATSOEVER, AND NATIONAL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY RELATING TO THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS PRIOR WRITTEN APPROVAL OF THE CHIEF EXECUTIVE OFFICER AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

Life support devices or systems are devices which (a) are intended for surgical implant into the body, or (b) support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in a significant injury to the user. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system or to affect its safety or effectiveness.

National Semiconductor and the National Semiconductor logo are registered trademarks of National Semiconductor Corporation. All other brand or product names may be trademarks or registered trademarks of their respective holders.

Copyright© 2011 National Semiconductor Corporation

For the most current product information visit us at www.national.com



National Semiconductor Americas Technical Support Center Email: support@nsc.com Tel: 1-800-272-9959 National Semiconductor Europe Technical Support Center Email: europe.support@nsc.com National Semiconductor Asia Pacific Technical Support Center Email: ap.support@nsc.com

National Semiconductor Japan Technical Support Center Email: jpn.feedback@nsc.com

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products	Applications
----------	--------------

Audio www.ti.com/audio Communications and Telecom www.ti.com/communications **Amplifiers** amplifier.ti.com Computers and Peripherals www.ti.com/computers dataconverter.ti.com Consumer Electronics www.ti.com/consumer-apps **Data Converters DLP® Products** www.dlp.com **Energy and Lighting** www.ti.com/energy DSP dsp.ti.com Industrial www.ti.com/industrial Clocks and Timers www.ti.com/clocks Medical www.ti.com/medical Interface interface.ti.com Security www.ti.com/security

Logic logic.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Power Mgmt power.ti.com Transportation and Automotive www.ti.com/automotive
Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID <u>www.ti-rfid.com</u>

OMAP Mobile Processors <u>www.ti.com/omap</u>

Wireless Connectivity www.ti.com/wirelessconnectivity

TI E2E Community Home Page e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2011, Texas Instruments Incorporated